



New MCP Part Number Matrix

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MICROSEMI CORPORATION

Memory Family

- 2 = SSRAM 7 = Flash
- 3 = SDRAM 8 = SRAM
- 4 = DRAM 9 = Combo (Mixed)
- 5 = EEPROM

Memory Type

- E = Double Data Rate Synchronous DRAM DDR-1
- H = Double Data Rate Synchronous DRAM DDR-2
- M = Mirror-bit Flash
- Z = NBL SSRAM

Depth

16M, 512K, etc.

Bus Width

x64, x72, etc.

Voltage

- V = 3.3
- S = 2.5
- E = 1.8

Options

- Blank = Unbuffered
- B = Bottom Boot Block (Flash only)
- E = Serial EEPROM (MCP only)
- R = Registered
- T = Top Boot Block (Flash only)

Speed / Data Rate

Frequency - SDRAM

- 66 = 66MHz 125 = 125MHz
- 100 = 100MHz 133 = 133MHz

Date Rate - DDR / DDR2 SDRAM

- 200 = 200Mb/s 400 = 400Mb/s
- 250 = 250Mb/s 533 = 533Mb/s
- 266 = 266Mb/s 667 = 667Mb/s
- 333 = 333Mb/s 800 = 800Mb/s

Package

- B = PBGA NB = PBGA (Thinned Stacked)
- B2 = PBGA (Shrink) ST = Stacked TSOP
- SB = PBGA (Stacked) T = TSOP

Temp Range

- C = 0°C to 70°C
- I = -40°C to +85°C
- M = -55°C to +125°C

RoHS Compliance

- Blank = Standard Process
- F = Lead Free
- G = RoHS Compliant
- R = RoHS-5 Compliant

Note: Lead Free process currently not available.

Note:

Not all packages, speeds and other options are available on every product. Please refer to the individual data sheet for option selection.